CLAIMS

1. A lamination process for applying a layer of metal particles comprising a layer of a composition to a component, comprising:

placing the component on a film comprising the layer of metal particles on a release coating film on a polymeric substrate to form an assembly, the layer of metal particles having a thickness of 100 to 300 micrometers after drying;

applying heat to the assembly in a range of 50 to 175 °C;

applying pressure to the assembly in a range of 0.05 to 3 MPa; and

releasing the component from the assembly, whereby the layer of metal particles remains on the component and separates from the polymeric substrate,

wherein the composition comprises paste, the paste comprises;

a metal powder having a d_{50} range of 0.001 to 10 micrometers, the metal powder contributing 30 to 95 wt% of the paste, the metal powder comprising silver;

a binder having a softening point between 50 and 170 °C, the binder contributing 0.1 to 5 wt% of the paste; and

a solvent possible to dissolve at least the binder.

2. The lamination process of claim 1, wherein the film comprising the layer of metal particles is the same size as the component.